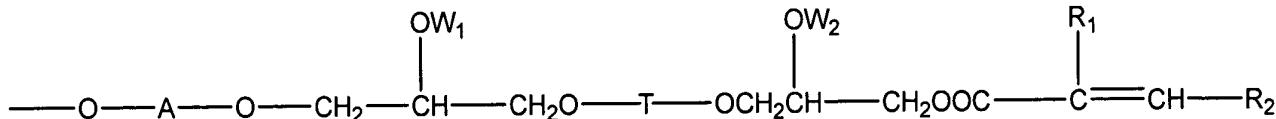


Amendments to the Specification:

Please add the following new paragraph on page 12, after line 6:

If n in formula IV is 0, then X is hydrogen and Y is the group of the formula



Please delete the paragraph on page 12, lines 7-18, and replace it with the following revised paragraph:

As the completely reacted epoxy acrylates of formula III contain almost no more epoxy groups, they can be reacted with cyclic anhydrides of polycarboxylic acids. In this case, the aliphatic hydroxyl groups react with the cyclic anhydride to effect ring opening and hemiester formation. In this reaction, for each reacted hydroxyl group a carboxylic acid bonded to the resin forms. The reaction comprises reacting the epoxy acrylate of formula III with the cyclic anhydride, in the absence or presence of a catalyst and of a polymerisation inhibitor, at elevated temperature. The HO groups of the compounds of formula II formula III are completely or partially acylated, accompanied by ring opening of the anhydride. It is therefore advantageous that the epoxy acrylates contain no more epoxy groups, otherwise gelation occurs. The anhydride is used in equimolar amounts with respect to the hydroxyl groups or in a less than equivalent amount. The reaction is known per se.

Please delete the last paragraph on page 13 and replace it with the following revised paragraph:

Owing to the unsaturated groups present in the molecule, the epoxy acrylates of formula III and the carboxyl group-containing epoxy acrylates of formula IV are thermally and photochemically crosslinkable in the presence of a photoinitiator such as Irgacure® 907 (2-methyl-1-[4-(methylthio) phenyl]-2-morpholino-propane-1), or any of the other photoinitiators described in U.S. Patent No. 5,942,371 (as incorporated by reference below) at column 9, line 46 to column 10, line 14. They can therefore be used and applied as acrylate components in photoresist formulations for the production of solder resists or primary resists by known methods, as for example disclosed in Swiss patent application 2005/93-4, filed on 2nd July 1993, entitled "Photopolymerisable compositions" (the U.S. counterpart of which issued as U.S. Patent

5,942,371 on August 24, 1999 hereby incorporated by reference), and give resist layers having enhanced thermal, mechanical, electrical and chemical properties. The resist formulations prepared therefrom are used in particular in the field of printed wiring boards as solder resists or primary resists, and of printing plates. They are also suitable for the production of offset printing plates, flexographic printing plates, book printing plates and screen printing formulations. Suitable developers are aqueous as well as aqueous-organic or organic systems. Owing to the presence of carboxyl groups in the compounds of formula IV, these systems are particularly suitable for the preparation of aqueous-alkaline developable photoresists.

Please delete the paragraph on page 27, lines 22-28, and replace it with the following revised paragraph:

Application Example

Formulation 1.1 comprises a novel acrylate modified with carboxyl groups:

53.00 g of the reaction product of Example 15 (as 55% solution in methoxypropyl acetate);
19.00 g of CN 965 (acrylate sold by Craynor);
3.00 g Irgacure 907 (2-methyl-1-[4-(methylthio)phenyl]-2-morpholino-propane-1) (photoinitiator; CIBA AG, Basel);
1.50 g Quantacure ITX (isopropylthioxanthone; sensitiser);